Title (en)

METHODS AND APPARATUS FOR HOLDING AND POSITIONING SEMICONDUCTOR WORKPIECES DURING ELECTROPOLISHING AND/OR ELECTROPLATING OF THE WORKPIECES

Title (de)

VERFAHREN UND VORRICHTUNG ZUR HALTERUNG UND POSITIONIERUNG VON HALBLEITERWERKSTÜCKEN BEIM ELEKTROPOLIEREN UND/ODER ELEKTROPLATTIEREN VON HALBLEITERWERKSTÜCKEN

Title (fr)

PROCEDES ET APPAREILS DEUPPORT ET DE POSITIONNEMENT DE PIECES A SEMICONDUCTEURS LORS DE LEUR POLISSAGE ELECTROLYTIQUE ET/OU DE LEUR PLACAGE PAR ELECTRODEPOSITION

Publication

EP 1133786 A2 20010919 (EN)

Application

EP 99965053 A 19991124

Priority

- US 9928106 W 19991124
- US 11013698 P 19981128

Abstract (en)

[origin: WO0033356A2] A wafer chuck assembly for holding a wafer during electroplating and/or electropolishing of the wafer includes a wafer chuck for receiving the wafer. The wafer chuck assembly also includes an actuator assembly for moving the wafer chuck between a first and a second position. When in the first position, the wafer chuck is opened. When in the second position, the wafer chuck is closed.

IPC 1-7

H01L 21/00; C25D 7/12

IPC 8 full level

C25D 7/12 (2006.01); **C25D 17/06** (2006.01); **C25D 17/08** (2006.01); **C25D 21/10** (2006.01); **C25F 7/00** (2006.01); **H01L 21/288** (2006.01); **H01L 21/3063** (2006.01); **H01L 21/321** (2006.01); **H01L 21/687** (2006.01)

CPC (source: EP KR)

H01L 21/2885 (2013.01 - EP); **H01L 21/32115** (2013.01 - EP); **H01L 21/68** (2013.01 - KR); **H01L 21/68721** (2013.01 - EP); **H01L 21/68785** (2013.01 - EP); **H01L 21/68792** (2013.01 - EP)

Citation (search report)

See references of WO 0033356A2

Cited by

US11545378B2

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

WO 0033356 A2 20000608; **WO 0033356 A3 20010712**; **WO 0033356 A9 20010802**; AU 3105400 A 20000619; CA 2352160 A1 20000608; CN 100382235 C 20080416; CN 1191605 C 20050302; CN 1346510 A 20020424; CN 1632914 A 20050629; EP 1133786 A2 20010919; IL 143316 A0 20020421; IL 143316 A 20050320; JP 2002531702 A 20020924; JP 2007119923 A 20070517; KR 100503553 B1 20050726; KR 100516776 B1 20050926; KR 100562011 B1 20060322; KR 20010086051 A 20010907; KR 20040070317 A 20040806; KR 20050013179 A 20050202; TW 430919 B 20010421

DOCDB simple family (application)

US 9928106 W 19991124; AU 3105400 A 19991124; CA 2352160 A 19991124; CN 200510003773 A 19991124; CN 99813794 A 19991124; EP 99965053 A 19991124; IL 14331699 A 19991124; JP 2000585913 A 19991124; JP 2006315540 A 20061122; KR 20017006569 A 20010525; KR 20047011238 A 19991124; KR 20057000594 A 19991124; TW 88120687 A 19991126